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The SiC power revolution is ready for high-volume car manufacturing

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Agenda

1 Motivation: The impact of global energy consumption

2 Silicon and compound semiconductor overview

3 Challenges of automotive electrification

4 800V accelerates SiC adoption in EV subsystems

5 Key SiC applications in EV

6 SiC MOSFET automotive technology

7 How car electrification impacts power semiconductors

8 ST SiC MOSFET manufacturing strategy

9 Key takeaways

Power & energy

ST technology and solutions enable customers to increase energy efficiency everywhere & support the use of renewable energy sources

Rising demand for and usage of electrical energy

Over **30%** global electricity demand increase from 2020 to 2030

Decrease carbon emissions to reduce global warming impact

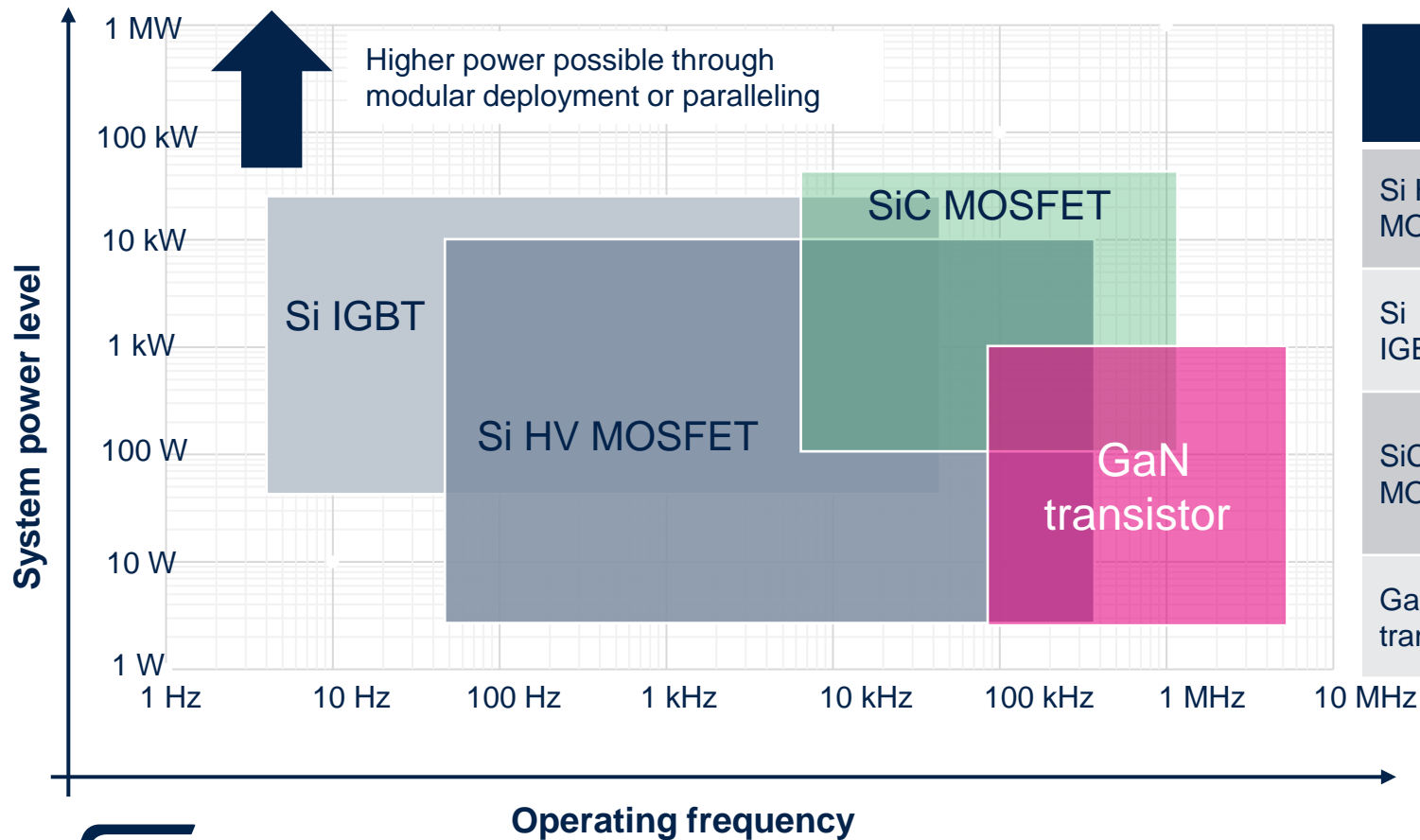
45% CO₂ emission reduction from 2010 to 2030 to limit warming to 1.5°C

Increase use of renewable energy

Electrical energy from renewal sources from **~10%** in 2020 to **~20%** in 2030

Silicon and wide-bandgap overview

Wide product range targeting automotive and industrial power applications



Automotive examples of power applications

Si HV MOSFET	DC-DC converter, low-power motor control, OBC, charging Station, DC link discharge ...
Si IGBT	HV motor control, PTC heating, traction inverter, DC link discharge...
SiC MOSFET	High power DC-DC converter, charging station, traction inverter, OBC, e-climate compressor, battery disconnect switch, smart power distribution, fuel cell (DC-DC and high-pressure pump), DC link discharge
GaN HEMT transistor	Class D amplifier, wireless charger DC-DC converter, OBC, LiDAR, ...

Si = Silicon; HV = High voltage; SiC = Silicon Carbide

SiC (and GaN next) targets energy-efficient applications

Wide-bandgap semiconductors offer superior performance and characteristics thanks to:

Faster switching

Lower switching losses and higher efficiency

Higher switching frequencies

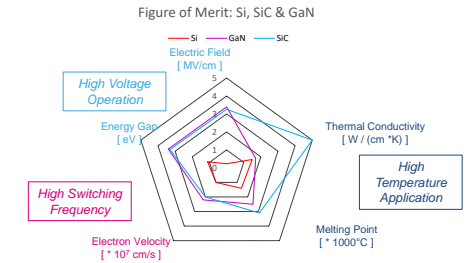
Smaller filters and magnetics

Higher operating voltages with low on-resistance

Reduced currents and lower conduction losses

Higher junction temperatures

Reduced cooling requirement



SiC and GaN

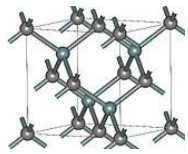
SiC

More than 25 years of focus on SiC in STMicroelectronics

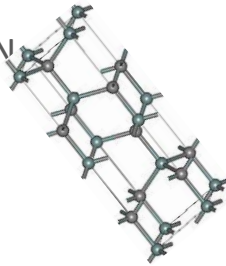
Si - Silicon

GaN - Gallium Nitride

SiC - Silicon Carbide



Si
Cubic



SiC
Hexagonal

Figure of Merit: Si, SiC & GaN

— Si — GaN — SiC
Electric Field [MV/cm]

High Voltage Operation

Energy Gap [eV]

High Switching Frequency

Electron Velocity [* 10⁷ cm/s]

Thermal Conductivity [W / (cm *K)]

High Temperature Application

Melting Point [* 1000°C]



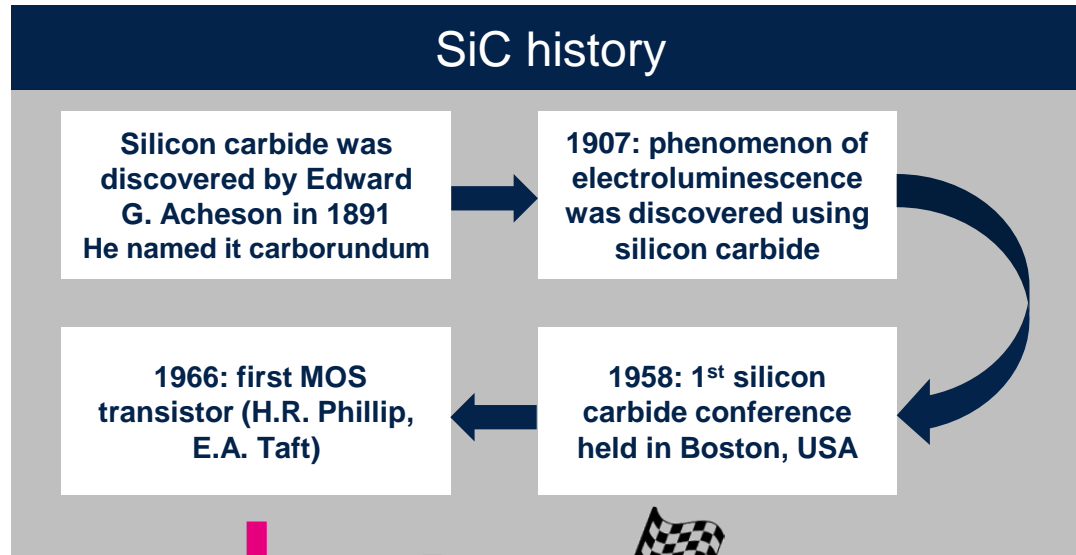
Oct 2022 Integrated substrate manufacturing facility in Italy

Dec 2020 3rd Gen MOSFET Qualification

June 2017 2nd Gen MOSFET start production

June 2014: 3rd Gen diode start production

September 2014: 1st Gen MOSFET start production

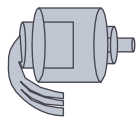


Challenges of electrification

Mobility is all about efficiency



Reduce weight and cost of cooling systems



Reduce power losses and heat dissipation



Extend driving range above 600 km



Reduce the number of recharges



Increase reliability

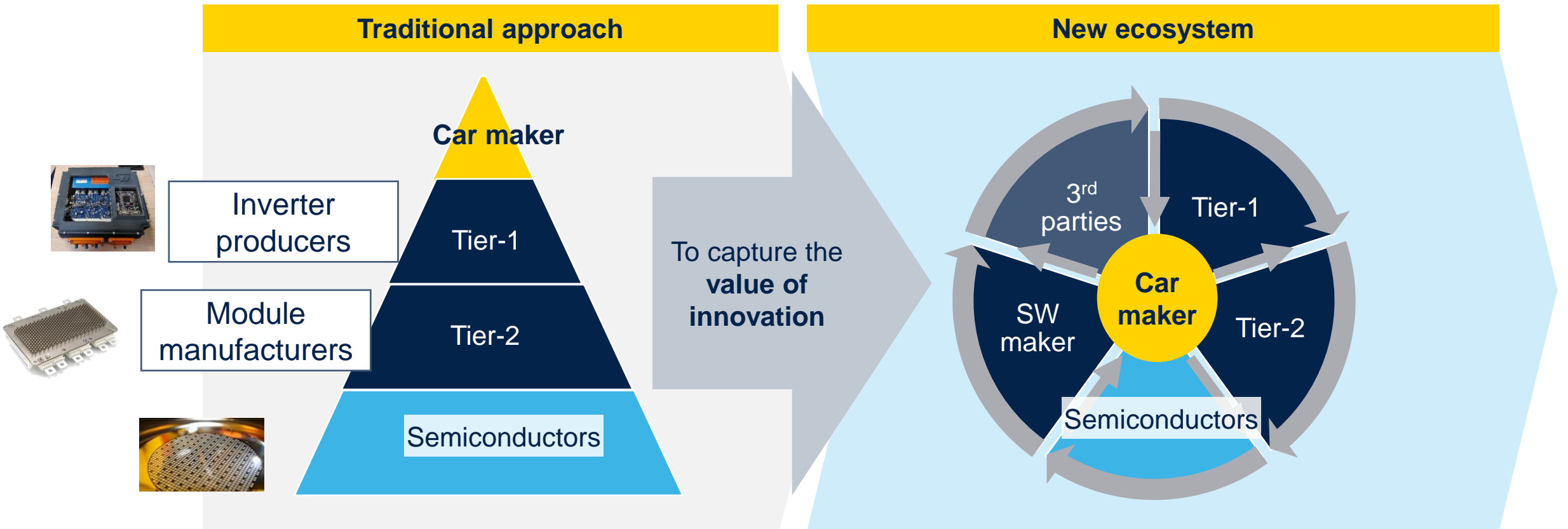


Cost reduction



From car makers to mobility providers

Vehicle content and car differentiation is strongly dependent on semiconductors



800V accelerates SiC adoption in EV subsystems

- Higher breakdown voltages more easily addressed by SiC
- System and component downsizing more easily realized with SiC
- At 800V, the benefit of low switching losses in SiC become more prevalent



Switch downsizing and system efficiency gain enabled by SiC increasing at 800V

400V /
160kW

~3x smaller semiconductor area

3-5% higher efficiency

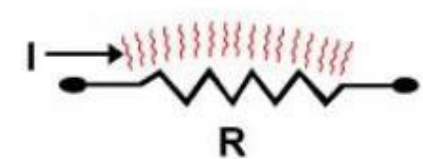
800V /
200kW

~5x smaller semiconductor area

8-12% higher efficiency

Widespread adoption of 800 V bus


Higher battery voltage in EV/HEV reduces losses in inverters and other EV subsystems, and facilitates faster charging

$$P = I^2R$$


The diagram shows a resistor symbol with current I entering from the left. Red wavy lines above the resistor represent heat loss. The equation $P = I^2R$ is positioned above the resistor.



Joule loss reduction

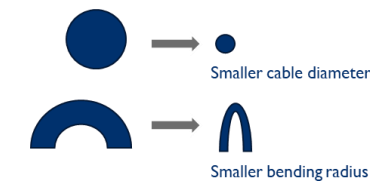
 Ultrafast charging enabler (down to about 20 min of charging time)

Power increase

- More powerful cars while keeping device currents down to acceptable levels
- Allows use components with lower current rating (higher voltage)
- Enables fast battery charging

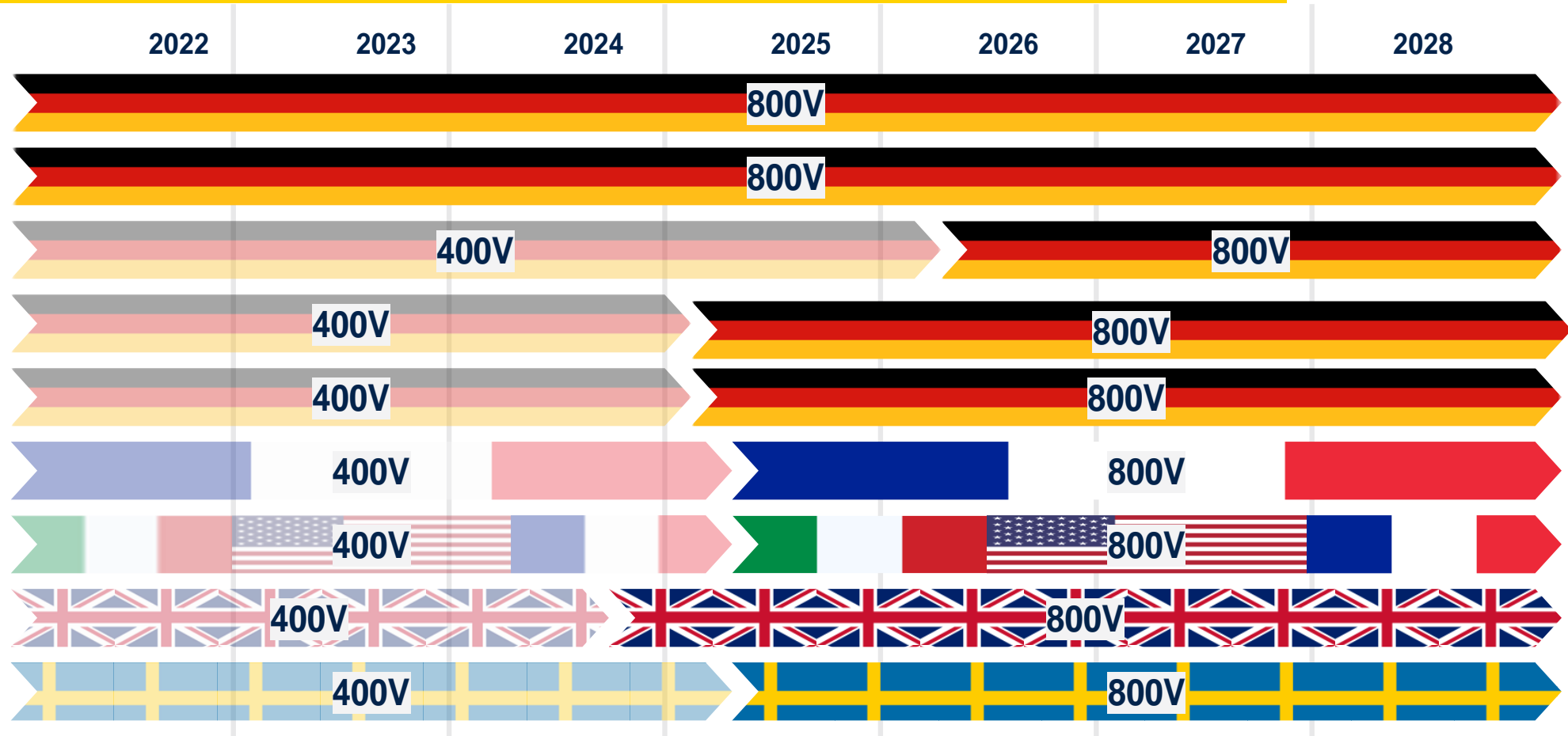
Cost and weight reduction

Easier integration in vehicle

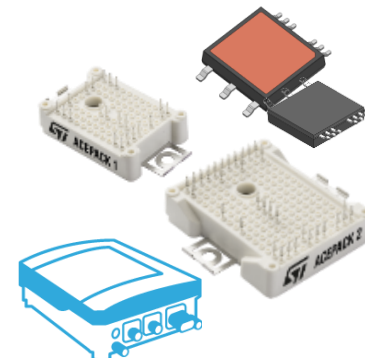
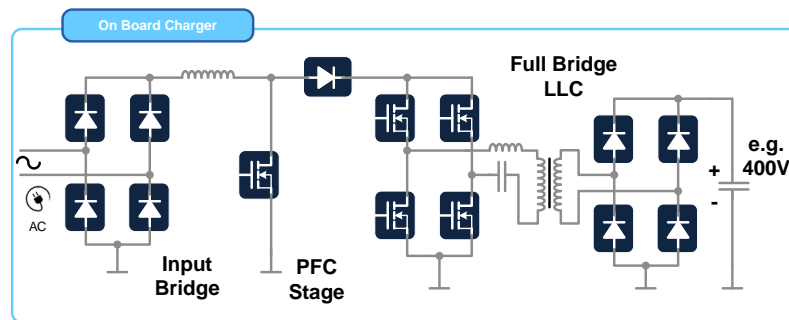
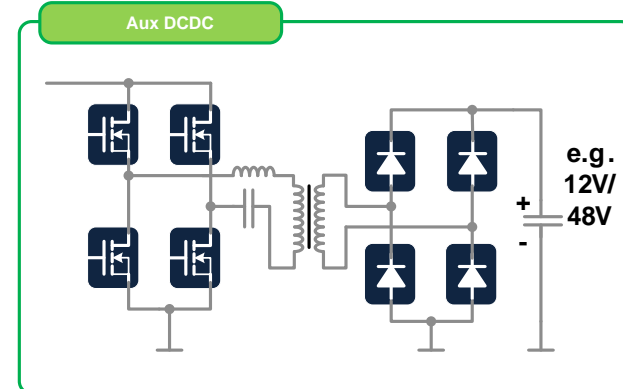
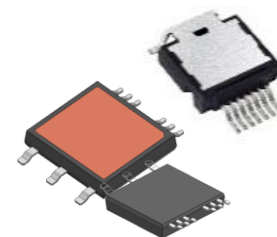
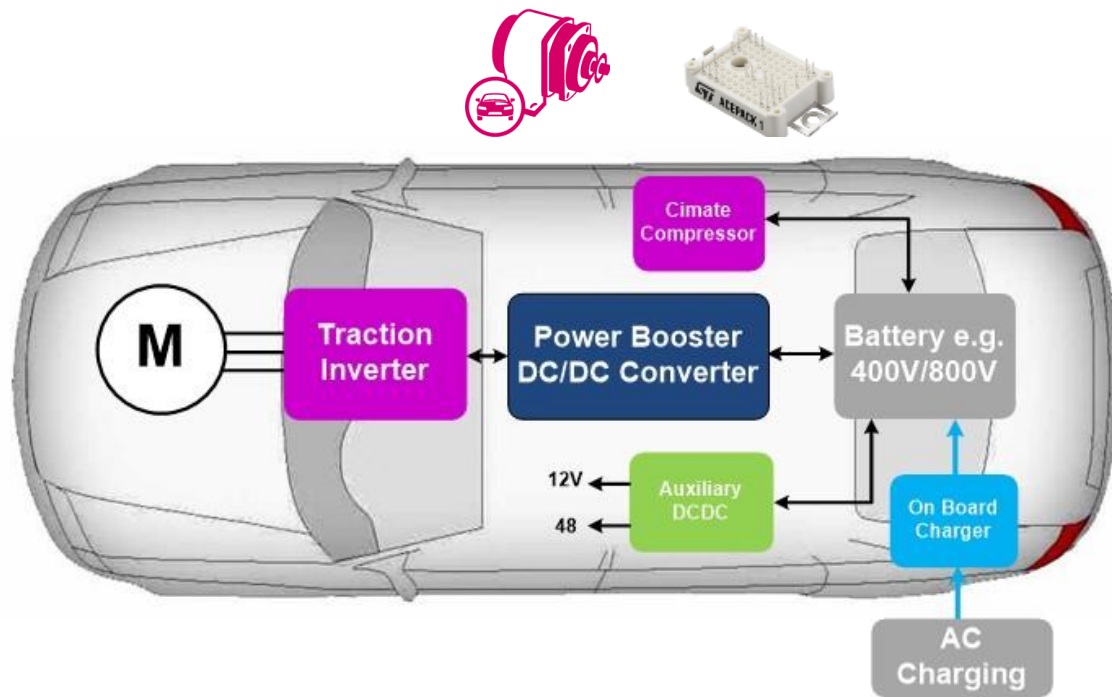
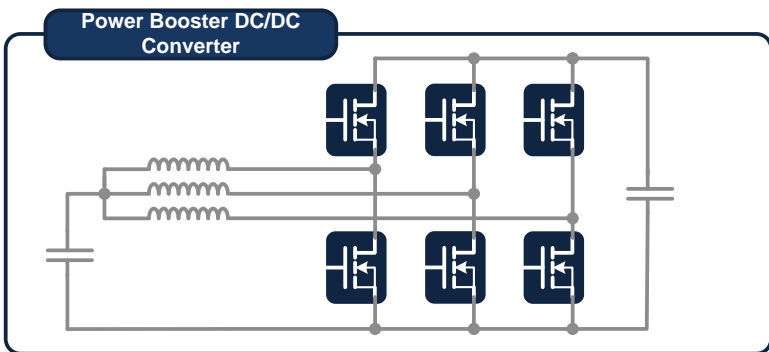
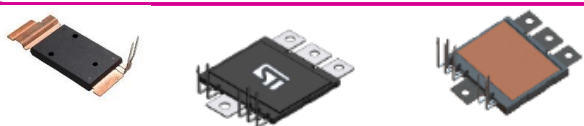
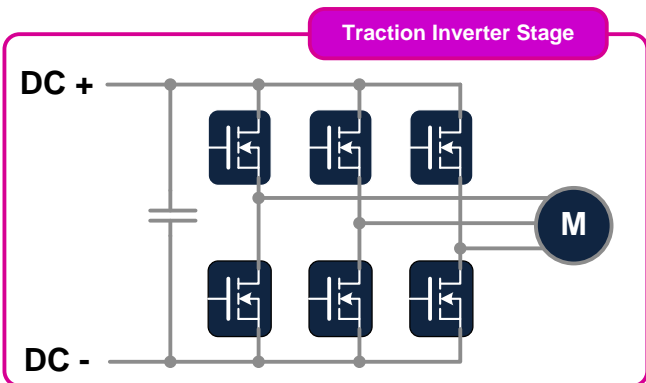


EMEA market DC BUS voltage evolution

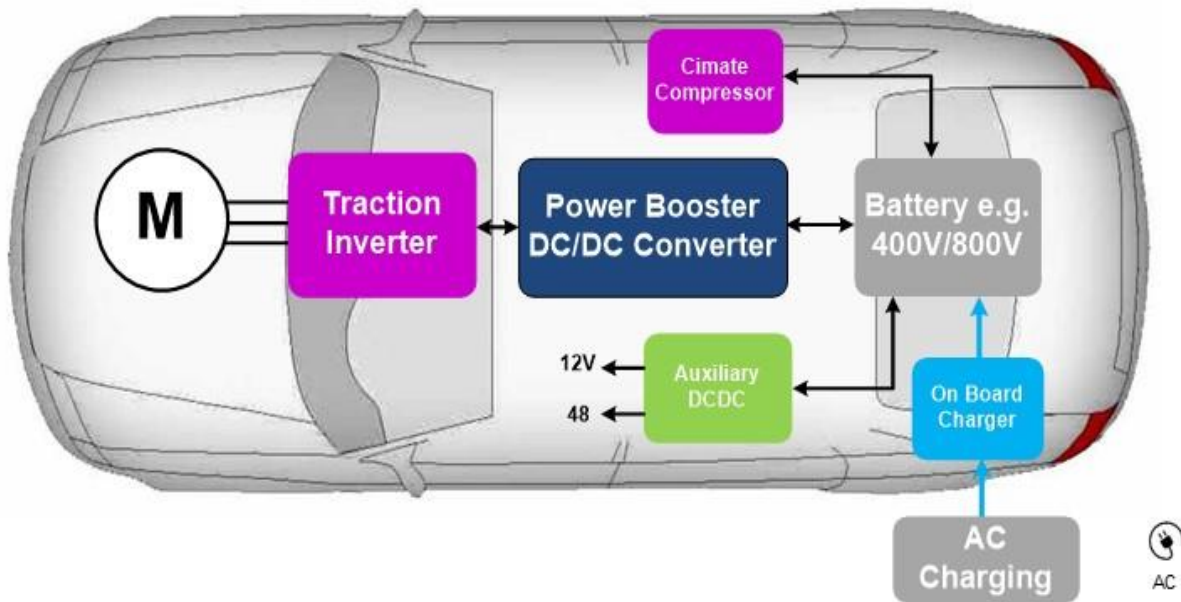
BUS voltage in EMEA converged to 800V in 2025 for BEV / PHEV very likely to stay on 400V



Key SiC applications in EV addressed by tailored packaging



New automotive application use cases powered by SiC



Fuel cell applications

- Interleaved power DCDC
- High Speed Pump

Battery disconnect

- Mechanical relay replacement / Solid State Contactors

DC link discharge

- Discharging HV due to safety requirements

Smart power distribution

- Protection of auxiliaries
- Boardnet optimization

Various

- Heating Control
- High Speed Pump (Turbo)

New applications
realized with SiC



>60% *
Today market share in automotive

Technology roadmap

Gen1	Optimized Ron and Tj for motor drive applications	■
Gen2	Balanced Ron and Qg for industrial and automotive	■
Gen3	Lower Ron vs. Gen2 maximizes the driving range of EVs	■
Gen4*	Reduced Ron vs. Gen3 tailored for traction inverter	■
Gen5**	Innovative high power density technology structure	■
MDSiC™ **	Radical innovation, outstanding Ron value at hot temperature and further Ron reduction vs. Gen5	■

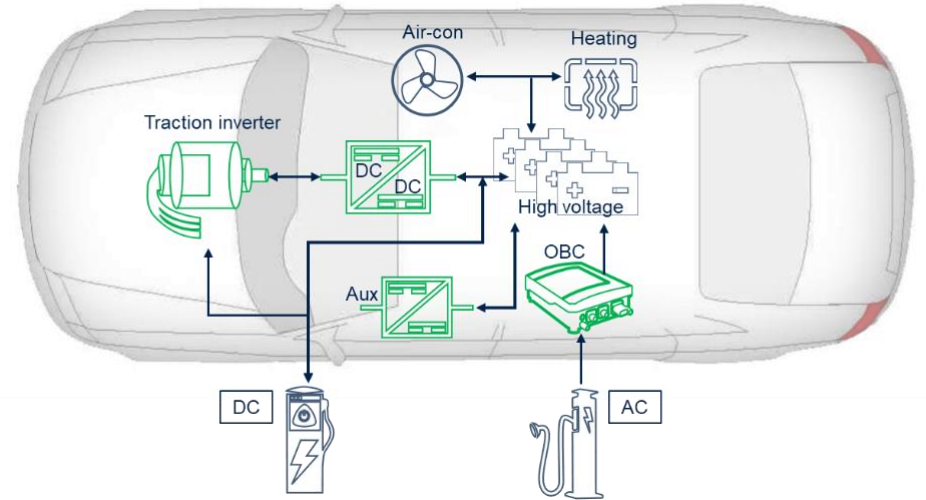
Gen4: Technology qualification >2023
 Gen5: Technology qualification >2025
 MDSiC: Technology qualification > 2027

Advanced packaging



* Source: Omdia - Power Discrete and Module Market prelim. 2022 – May 2023

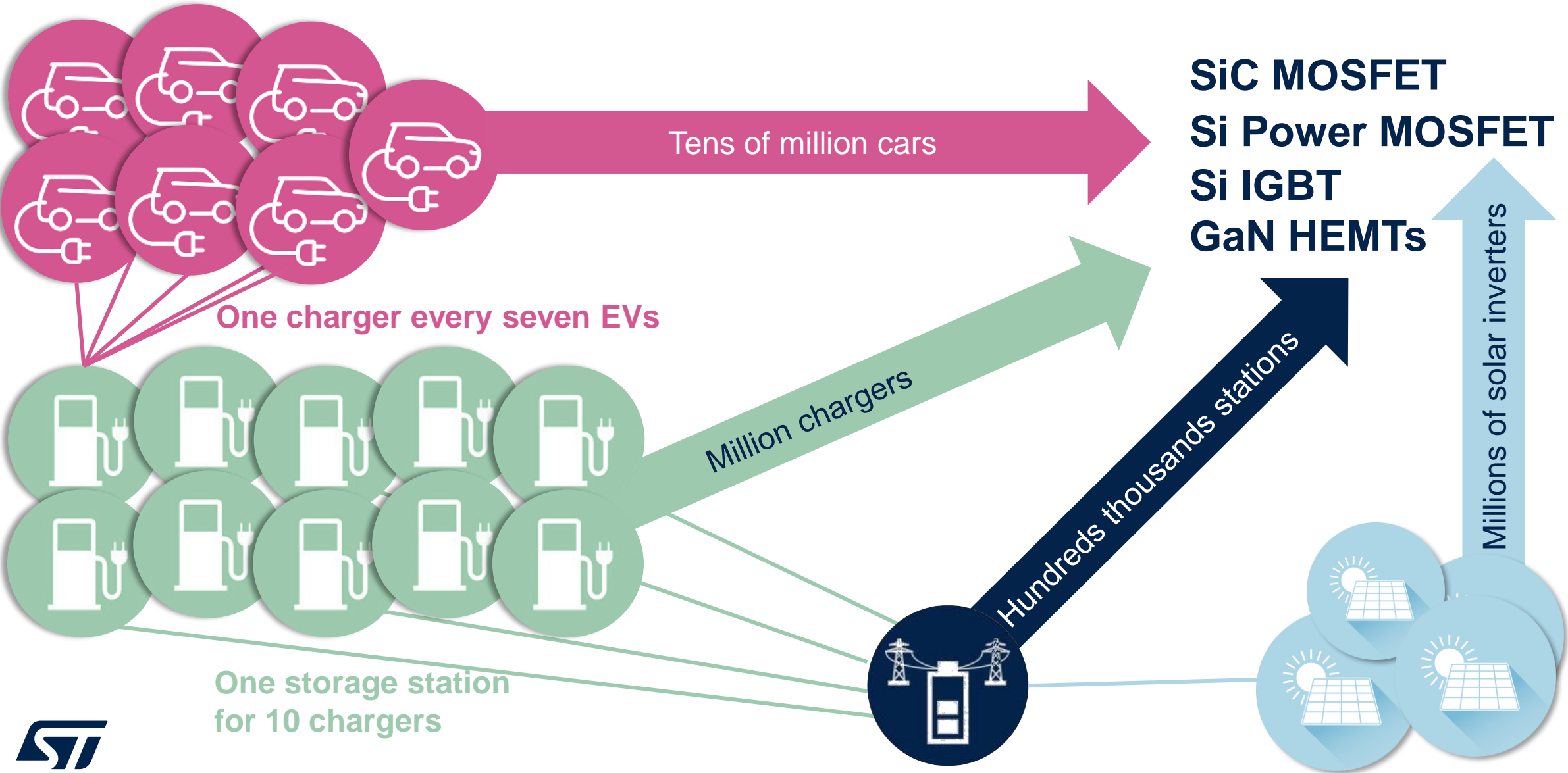
SiC MOSFET automotive technology






Traction inverter	From Gen2 to Gen5
DC-DC converters	From Gen1 to Gen5
OBC	From Gen2 to Gen5

*Under development ■ Planar ■ Not Planar
 ** R&D stage

How car electrification impacts power semiconductors



How car electrification impacts power semiconductors

	System	Power	Systems/vehicle			
	Traction inverter	100-250kW	1.5x	SiC MOSFET	Si IGBT	24-48 transistors
	OBC / DC-DC	11k-44kW	1x	SiC MOSFET	Si HV MOSFET	GaN HEMTs
	Charging station DC-DC	100k-250kW	0.15x	SiC MOSFET		12-18 transistors
	Energy storage	>1MW	0.015x	SiC MOSFET		>100 transistors

Power Transistors Market Outlook by macro technologies & focus applications



- Si MOSFET discrete (LV+HV)
- SiC MOSFET
- GaN power transistor
- IGBT
- IPM (all)
- Power Module (all)
- Power Bipolar

Industrial

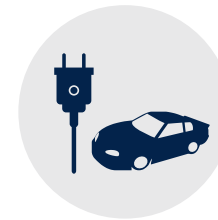
+6.4% CAGR (2023-27)
From 13B\$ to 16.7B\$



- Motor control and appliances
- SMPS and LED lighting
- 5G & datacenter power supplies
- Solar and energy storage
- Charging stations

Automotive

+15.1% CAGR (2023-27)
From 9.6B\$ to 16.8B\$

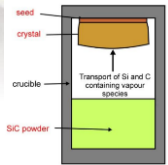
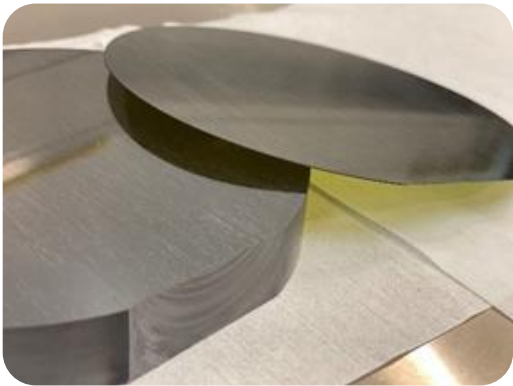


- Electric Vehicles
 - Traction inverters
 - DC-DC converters
 - On-board chargers
- Traditional automotive

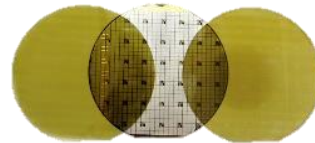
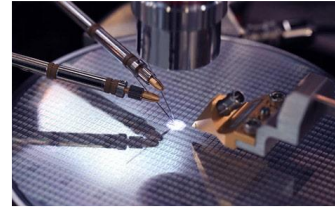
ST SiC MOSFET manufacturing strategy

Moving towards an integrated dual fab (**synoptic view**)

Substrate technology
From powder to ingot



Front-end technology
with Epy and EWS testing



Back-end technology
Bare dice, discrete, modules



Norrköping (R&D)

Catania substrate Fab
production in 2024

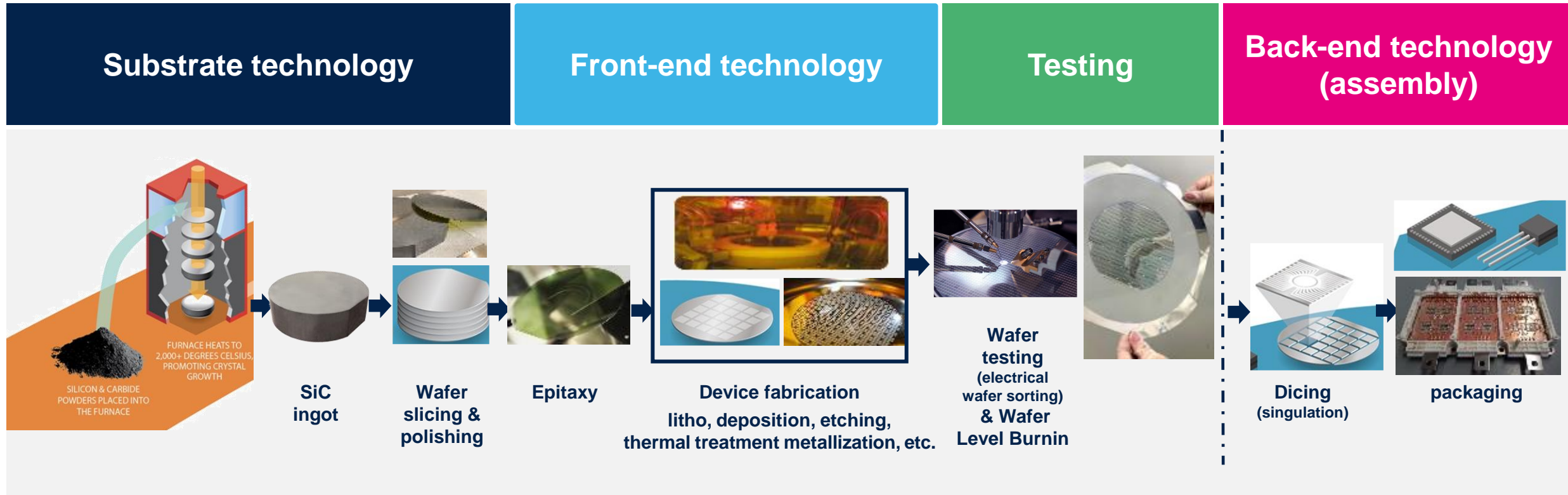
Catania

AMK (S'pore)

Shenzhen (China)

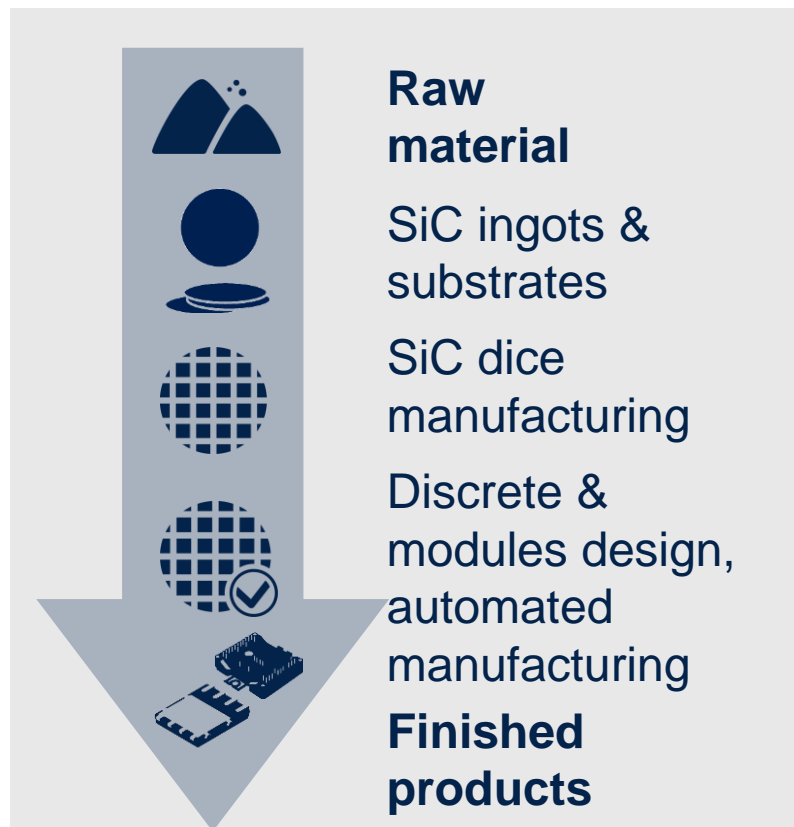
Bouskoura (Marocco)

SiC MOSFET vertical integration from powder to final product



Vertically integrating for supply chain robustness

Improving process control and efficiency, from powder to final product



SiC substrate R&D plant


Norrköping



- 150 mm production
- 200 mm with industrial quality and yields

New SiC integrated plant

Catania



- Pilot production in 2023
- 150 mm substrates + epitaxy (converting capability to 200 mm)

ST and Sanan Optoelectronics joint venture agreement

ST and Sanan Optoelectronics have signed an agreement* to create a 200mm silicon carbide (SiC) device manufacturing Joint Venture in Chongqing, China



- Supporting the rising demand in China for **car electrification and industrial power and energy** applications
- **Production** to start in **Q4 2025** and **full buildout** is anticipated in **2028**
- JV to serve as a **dedicated foundry** to ST for its Chinese customers
 - Making SiC devices **exclusively for ST**
 - Using ST proprietary SiC **manufacturing process technology**
- Total amount for full buildout of the JV is expected to be **~\$3.2B**, including **Capex of ~\$2.4B** over the next 5 years
 - Financed by contributions from **ST and Sanan**, local government support and loans to the JV
- Sanan to build & operate separately a **200mm SiC substrate plant**, using its own SiC substrate process, to fulfill the JV needs

*The completion of the project is subject to regulatory approvals.

Key takeaways

The EV market is growing $> +15\%$ CAGR for automotive power semiconductors from 2023 - 2027 and ST today is market leader in SiC MOSFETs. OEM ecosystem changes: **from buy to make model**

Silicon carbide is already driving car electrification: inverter, OBC, DC-DC converter... additional applications are ramping up

WBG semiconductor content in EV application grows in the coming years and lifetime requirement is being expanded continuously

DC Bus voltage converges to higher DC link voltages: around 2025-27 the majority of European OEM has an 800V system

Vertical integration is key to be competitive and to deliver high volumes

Our technology starts with You



Find out more at www.st.com/stpower

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